Amendments to the Claims

This listing of claims will replace all prior versions and listings of claims in the application.

Listing of Claims

1-12. (Cancelled)

13. (Currently Amended) A prepreg comprising:

a short fiber nonwoven fabric comprising thermal-resistant synthetic fibers;

an inorganic binder; and

a resin varnish,

wherein the prepreg is manufactured by bonding the synthetic fibers with the inorganic binder, and after the bonding impregnating the nonwoven fabric with a resin varnish[.], wherein the thermal-resistant synthetic fibers intersect each other forming intersections; wherein the thermal-resistant synthetic fibers are bound with the inorganic binder at the intersections.

14. (Original) The prepreg according to claim 13, wherein the resin varnish is at least one selected from the group consisting of an epoxy resin, a polyimide resin, a phenol resin, a fluorine resin, and a cyanate ester resin.

15. (Canceled)

16. (Original) The prepreg according to claim 13, wherein the thermal-resistant synthetic fibers are at least one kind of fibers selected from the group consisting of poly(p-phenylene-2,6-benzobisoxazole) fibers, polybenzimidazole fibers, aramid fibers, polytetrafluoroethylene fibers, and poly(p-phenylene-2,6-benzobisthiazole) fibers.

17. (Original) The prepreg according to claim 13, wherein the inorganic binder is a residue formed from either a solution of low melting point glass or a water-dispersible colloidal solution

in which at least either fibers of low melting point glass or particles of low melting point glass are dispersed.

18. (Original) The prepreg according to claim 13, wherein the fibers are bound with a chemical covalent siloxane bonding.

19. (Original) The prepreg according to claim 13, wherein the content of the inorganic binder ranges from 5 to 40 weight parts when the thermal-resistant synthetic fibers are 100 weight parts.

20. (Original) The prepreg according to claim 13, wherein the fineness of the thermal-resistant synthetic fibers ranges from 0.25 to 4 denier.

21. (Original) The prepreg according to claim 13, wherein the length of the thermal-resistant synthetic fibers ranges from 1 to 6mm.

22. (Original) The prepreg according to claim 13, wherein the nonwoven fabric is obtained by a wet formation method.

23. (Original) The prepreg according to claim 13, wherein the weight of the prepreg ranges from 40 to 200g/m^2.

24. (Original) The prepreg according to claim 13, wherein the average thickness of the prepreg ranges from 0.04 to 0.2mm.

25. (Currently amended) A circuit board comprising a prepreg as an insulator, wherein the prepreg is prepared from a nonwoven fabric comprising short fibers bound with an inorganic binder, by impregnating the nonwoven fabric with a resin varnish[.],

wherein the thermal-resistant synthetic fibers intersect each other forming intersections; wherein the thermal-resistant synthetic fibers are bound with the inorganic binder at the intersections.

26. (Original) The circuit board according to claim 25, wherein the resin varnish is at least one selected from the group consisting of an epoxy resin, a polyimide resin, a phenol resin, a fluorine resin and a cyanate ester resin.

27. (Canceled)

28. (Original) The circuit board according to claim 25, wherein the thermal resistant synthetic fibers are at least one kind of fibers selected from the group consisting of poly(p-phenylene-2,6-benzobisoxazole) fibers, polybenzimidazole fibers, aramid fibers, polytetrafluoroethylene fibers, and poly(p-phenylene-2,6-benzobisthiazole) fibers.

29. (Original) The circuit board according to claim 25, wherein the inorganic binder is a residue formed from either a solution of low melting point glass or a water-dispersible colloidal solution in which at least either fibers of low melting point glass or particles of low melting point glass are dispersed.

30. (Original) The circuit board according to claim 25, wherein the fibers are bound with a chemical covalent siloxane bonding.

31. (Original) The circuit board according to claim 25, wherein the content of the inorganic binder ranges from 5 to 40 weight parts when the thermal-resistant synthetic fibers are 100 weight parts.

32. (Original) The circuit board according to claim 25, wherein the fineness of the thermal-resistant synthetic fibers ranges from 0.25 to 4 denier.

33. (Original) The circuit board according to claim 25, wherein the length of the thermal-resistant synthetic fibers ranges from 1 to 6mm.

34. (Original) The circuit board according to claim 25, wherein the nonwoven fabric is obtained by a wet formation method.

35. (Original) The circuit board according to claim 25, wherein the weight of the circuit board ranges from 45 to 400 g/m^2.

36. (Original) The circuit board according to claim 25, wherein the average thickness of the circuit board ranges from 0.05 to 2mm.

37. (New) The prepreg according to claim 13, wherein the inorganic binder is a low melting point glass.

38. (New) The circuit board according to claim 25, wherein the inorganic binder is a low melting point glass.

39. (New) A prepreg comprising:

a short fiber nonwoven fabric comprising thermal-resistant synthetic fibers;

an inorganic binder; and

a resin varnish,

wherein the thermal-resistant synthetic fibers intersect each other forming intersections; wherein the thermal-resistant synthetic fibers are bound with the inorganic binder at the intersections.

40. (New) The prepreg according to claim 39, wherein the resin varnish is at least one selected from the group consisting of an epoxy resin, a polyimide resin, a phenol resin, a fluorine resin and a cyanate ester resin.

41. (New) The prepreg according to claim 39, wherein the thermal-resistant synthetic fibers are at least one kind of fibers selected from the group consisting of poly(p-phenylene-2,6-benzobisoxazole) fibers, polybenzimidazole fibers, aramid fibers, polytetrafluoroethylene fibers, and poly(p-phenylene-2,6-benzobisthiazole) fibers.

42. (New) The prepreg according to claim 39, wherein the inorganic binder is a residue formed from either a solution of low melting point glass or a water-dispersible colloidal solution in which at least either fibers of low melting point glass or particles of low melting point glass are dispersed.

43. (New) The prepreg according to claim 39, wherein the fibers are bound with a chemical covalent siloxane bonding.

44. (New) The prepreg according to claim 39, wherein the content of the inorganic binder ranges from 5 to 40 weight parts when the thermal-resistant synthetic fibers are 100 weight parts.

45. (New) The prepreg according to claim 39, wherein the fineness of the thermal-resistant synthetic fibers ranges from 0.25 to 4 denier.

46. (New) The prepreg according to claim 39, wherein the length of the thermal-resistant synthetic fibers ranges from 1 to 6mm.

47. (New) The prepreg according to claim 39, wherein the nonwoven fabric is obtained by a wet formation method.

48. (New) The prepreg according to claim 39, wherein the weight of the prepreg ranges from 40 to 200g/m^2.

49. (New) The prepreg according to claim 39, wherein the average thickness of the prepreg ranges from 0.04 to 0.2mm.

50. (New) The prepreg according to claim 39, wherein the inorganic binder is a low melting point glass.

51. (New) A circuit board comprising:

an insulator, and

wiring pattern on the insulator,

wherein the insulator comprises a short fiber nonwoven fabric comprising thermal-resistant synthetic fibers, an inorganic binder, and a resin varnish,

wherein the thermal-resistant synthetic fibers intersect each other forming intersections; wherein the thermal-resistant synthetic fibers are bound with the inorganic binder at the intersections.

52. (New) The circuit board according to claim 51, wherein the resin varnish is at least one selected from the group consisting of an epoxy resin, a polyimide resin, a phenol resin, a fluorine resin and a cyanate ester resin.

53. (New) The circuit board according to claim 51, wherein the thermal resistant synthetic fibers are at least one kind of fibers selected from the group consisting of poly(p-phenylene-2,6-benzobisoxazole) fibers, polybenzimidazole fibers, aramid fibers, polytetrafluoroethylene fibers, and poly(p-phenylene-2,6-benzobisthiazole) fibers.

54. (New) The circuit board according to claim 51, wherein the inorganic binder is a residue formed from either a solution of low melting point glass or a water-dispersible colloidal solution in which at least either fibers of low melting point glass or particles of low melting point glass are dispersed.

55. (New) The circuit board according to claim 51, wherein the fibers are bound with a chemical covalent siloxane bonding.

56. (New) The circuit board according to claim 51, wherein the content of the inorganic binder ranges from 5 to 40 weight parts when the thermal-resistant synthetic fibers are 100 weight parts.

57. (New) The circuit board according to claim 51, wherein the fineness of the thermal-resistant synthetic fibers ranges from 0.25 to 4 denier.

58. (New) The circuit board according to claim 51, wherein the length of the thermal-resistant synthetic fibers ranges from 1 to 6mm.

59. (New) The circuit board according to claim 51, wherein the nonwoven fabric is obtained by a wet formation method.

60. (New) The circuit board according to claim 51, wherein the weight of the circuit board ranges from 45 to 400g/m^2.

61. (New) The circuit board according to claim 51, wherein the average thickness of the circuit board ranges from 0.05 to 2mm.

62. (New) The circuit board according to claim 51, wherein the inorganic binder is a low melting point glass.